

# **Dual General Purpose Transistor MBT3906DW1**

The MBT3906DW1 device is a spin-off of our popular SOT-23/SOT-323 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-363 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

#### **Features**

- h<sub>FE</sub>, 100-300
- Low  $V_{CE(sat)}$ ,  $\leq 0.4 \text{ V}$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Available in 8 mm, 7-inch/3,000 Unit Tape and Reel
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and **PPAP** Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CEO}$	-40	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-40	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Curren-Continuous	I <sub>C</sub>	-200	mAdc
Electrostatic Discharge	ESD	HBM Class 2 MM Class B	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Package Dissipation (Note 1) T <sub>A</sub> = 25 °C	P <sub>D</sub>	150	mW
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	833	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

<sup>1.</sup> Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.

1



SOT-363/SC-88 **CASE 419B** STYLE 1

#### **MARKING DIAGRAM**



XX = Device Code M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

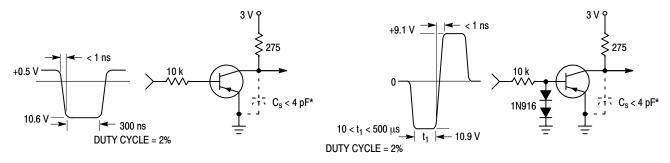
See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25$ °C unless otherwise noted)

	Characteristic	Symbol	Min	Max	Unit
OFF CHARACTE	RISTICS				1
Collector-Emitter I	Breakdown Voltage (Note 2)	V <sub>(BR)CEO</sub>	-40	-	Vdc
Collector-Base Br	eakdown Voltage	V <sub>(BR)</sub> CBO	-40	-	Vdc
Emitter-Base Brea	kdown Voltage	V <sub>(BR)EBO</sub>	-5.0	-	Vdc
Base Cutoff Curre	nt	I <sub>BL</sub>	_	-50	nAdc
Collector Cutoff Cu	urrent	I <sub>CEX</sub>	-	-50	nAdc
ON CHARACTE	RISTICS (Note 2)	1		•	
$(I_C = -1.0 \text{ mAdc})$ $(I_C = -10 \text{ mAdc})$ $(I_C = -50 \text{ mAdc})$	, V <sub>CE</sub> = -1.0 Vdc) , V <sub>CE</sub> = -1.0 Vdc) V <sub>CE</sub> = -1.0 Vdc) V <sub>CE</sub> = -1.0 Vdc) c, V <sub>CE</sub> = -1.0 Vdc)	h <sub>FE</sub>	60 80 100 60 30	- 300 - -	-
$(I_C = -10 \text{ mAdc},$	Saturation Voltage I <sub>B</sub> = -1.0 mAdc) I <sub>B</sub> = -5.0 mAdc)	V <sub>CE(sat)</sub>	- -	-0.25 -0.4	Vdc
	uration Voltage I <sub>B</sub> = -1.0 mAdc) I <sub>B</sub> = -5.0 mAdc)	V <sub>BE(sat)</sub>	-0.65 -	-0.85 -0.95	Vdc
SMALL-SIGNAL	CHARACTERISTICS				
Current-Gain-Ban	dwidth Product	f <sub>T</sub>	250	-	MHz
Output Capacitano	ee	C <sub>obo</sub>	-	4.5	pF
Input Capacitance		C <sub>ibo</sub>	-	10.0	pF
Input Impedance (V <sub>CE</sub> = -10 Vdc,	I <sub>C</sub> = -1.0 mAdc, f = 1.0 kHz)	h <sub>ie</sub>	2.0	12	kΩ
Voltage Feedback (V <sub>CE</sub> = −10 Vdc,	Ratio $I_C = -1.0$ mAdc, $f = 1.0$ kHz)	h <sub>re</sub>	0.1	10	X 10 <sup>-4</sup>
Small – Signal Curr (V <sub>CE</sub> = -10 Vdc,	rent Gain I <sub>C</sub> = -1.0 mAdc, f = 1.0 kHz)	h <sub>fe</sub>	100	400	-
Output Admittance $(V_{CE} = -10 \text{ Vdc}, I_{C} = -1.0 \text{ mAdc}, f = 1.0 \text{ kHz})$		h <sub>oe</sub>	3.0	60	μmhos
Noise Figure (V <sub>CE</sub> = −5.0 Vdc	s, I <sub>C</sub> = -100 μAdc, R <sub>S</sub> = 1.0 k Ω, f = 1.0 kHz)	NF	-	4.0	dB
SWITCHING CHA	ARACTERISTICS				
Delay Time	(V <sub>CC</sub> = -3.0 Vdc, V <sub>BE</sub> = 0.5 Vdc)	t <sub>d</sub>			
Rise Time	(I <sub>C</sub> = -10 mAdc, I <sub>B1</sub> = -1.0 mAdc)	t <sub>r</sub>	-	35	ns
Storage Time	$(V_{CC} = -3.0 \text{ Vdc}, I_C = -10 \text{ mAdc})$	t <sub>s</sub>	-	225	ne
Fall Time	$(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$	t <sub>f</sub>	-	75	ns

Fall Time  $(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$ 2. Pulse Test: Pulse Width  $\leq 300 \mu s$ ; Duty Cycle  $\leq 2.0\%$ .



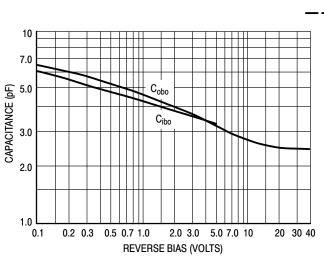
\* Total shunt capacitance of test jig and connectors

Figure 1. Delay and Rise Time Equivalent Test Circuit

Figure 2. Storage and Fall Time Equivalent Test Circuit

#### TYPICAL TRANSIENT CHARACTERISTICS

T<sub>J</sub> = 25°C
 T<sub>J</sub> = 125°C



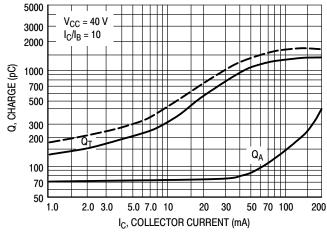
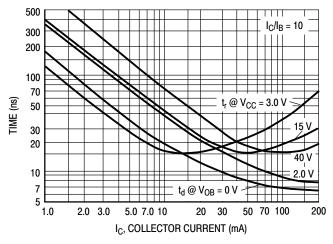


Figure 3. Capacitance

Figure 4. Charge Data



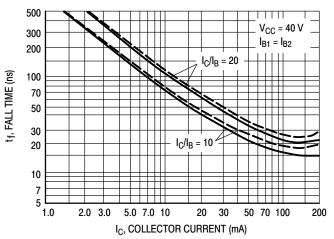
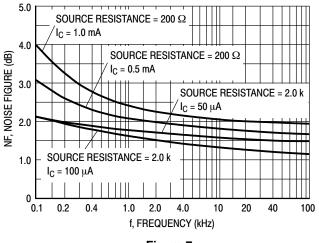


Figure 5. Turn - On Time

Figure 6. Fall Time

# TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$ 



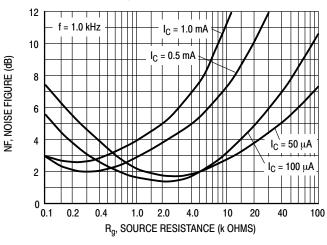
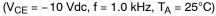
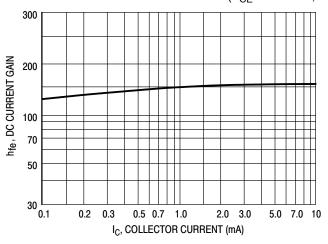


Figure 7.

Figure 8.

### **h PARAMETERS**





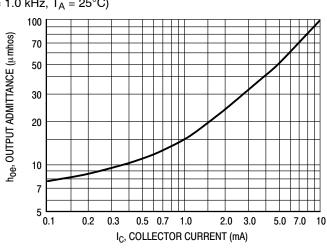
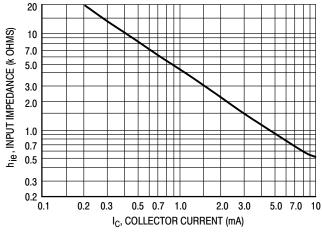


Figure 9. Current Gain

Figure 10. Output Admittance



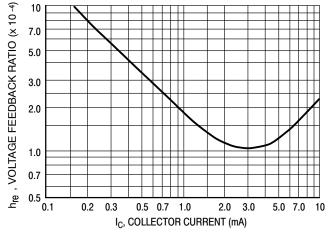


Figure 11. Input Impedance

Figure 12. Voltage Feedback Ratio

### TYPICAL STATIC CHARACTERISTICS

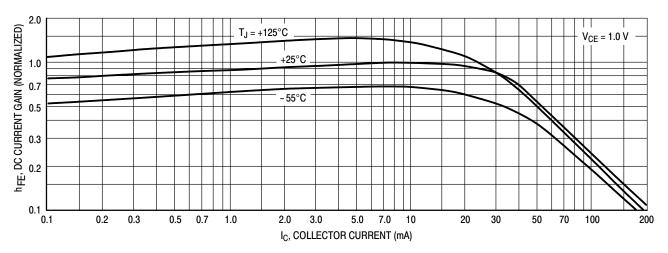


Figure 13. DC Current Gain

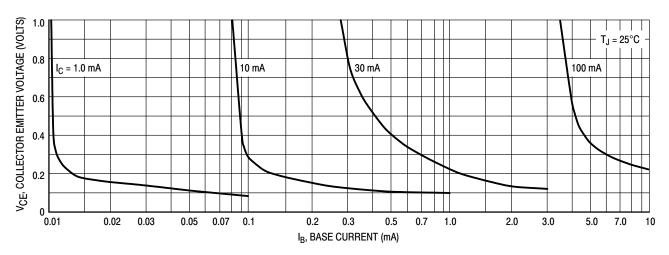


Figure 14. Collector Saturation Region

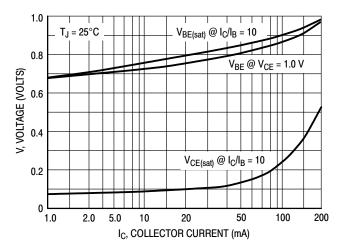


Figure 15. "ON" Voltages

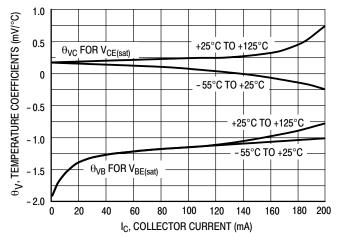


Figure 16. Temperature Coefficients

## **DEVICE ORDERING INFORMATION**

Device	Marking	Pin Out	Package	Shipping <sup>†</sup>
MBT3906DW1T1G	A2	6 5 4	SOT-363 (Pb-Free)	3000 / Tape & Reel
SMBT3906DW1T1G	A2	6 5 4	SOT-363 (Pb-Free)	3000 / Tape & Reel
SMBT3906DW3T1G	A3	6 5 4	SOT-363 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **REVISION HISTORY**

Revision	Description of Changes	Date
8	Rebranded the Data Sheet to <b>onsemi</b> format	7/7/2025

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.





E1

6X 0.30 -

e

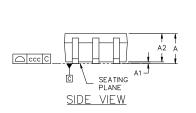
В

#### SC-88 2.00x1.25x0.90, 0.65P CASE 419B-02 **ISSUE Z**

**DATE 18 APR 2024** 

#### NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS.
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
- DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
  DATUMS A AND B ARE DETERMINED AT DATUM H.
- DIMENSIONS 6 AND C APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP. 6.
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.



TOP VIEW

∆aaa H A−B

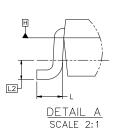
<u></u> БЬБ С

⊕ ddd M C A−B D

6X 0.66

2.50





	MILLIMETERS			
DIM	MIN.	NOM.	MAX.	
Α			1.10	
A1	0.00		0.10	
A2	0.70	0.90	1.00	
b	0.15	0.20	0.25	
С	0.08	0.15	0.22	
D	2.00 BSC			
E	2.10 BSC			
E1	1.25 BSC			
е		0.65 BSC	;	
L	0.26	0.36	0.46	
L2	0.15 BSC			
aaa	0.15			
bbb	0.30			
ccc	0.10			
ddd	0.10			

# **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

- \*Date Code orientation and/or position may vary depending upon manufacturing location.
- \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

# RECOMMENDED MOUNTING FOOTPRINT\*

FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

#### **STYLES ON PAGE 2**

DOCUMENT NUMBER:	98ASB42985B	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.65P		PAGE 1 OF 2	

onsemi and ONSEMi, are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or quarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

## SC-88 2.00x1.25x0.90, 0.65P CASE 419B-02 ISSUE Z

**DATE 18 APR 2024** 

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

DOCUMENT NUMBER:	98ASB42985B Electronic versions are uncontrolled except when accessed directly from the Document Repose Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.65P		PAGE 2 OF 2

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI., and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems. or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$ 

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales